



## [WeB2] Advanced Etch II

<b>Session Date</b>	November 12 (Wed.), 2025
<b>Session Time</b>	14:10-15:35
<b>Session Room</b>	Room B (Grand Ballroom 1, 2F)
<b>Session Chair</b>	Dr. Dongsoo Lee (Lam Research Korea, Korea)

### [WeB2-1] [Invited]

14:10-14:40

#### **Advanced Patterning of Metal Oxide Semiconductors for Memory Applications: IBE, RIE, and ALE Approaches**

Jie Li, Shreya Kundu, Laurent Souriau, Yiqun Wan, Attilio Belmonte, and Katia Devriendt (imec, Belgium)

### [WeB2-2] [Invited]

14:40-15:05

#### **r-Wave Resonance-Enhanced ICP Etcher for High-Precision Dry Etching**

Taeho Shin (ICD Ltd., Korea)

### [WeB2-3]

15:05-15:20

#### **Crystalline Ultra-Thin High-K Films Enabled by Fluorine-Radical-Based Atomic Layer Etching**

Somyeong Shin, Chang Kyu Lee, Chan Lee, Hyeonjin Cha, Byung Chul Cho, Ju Hwan Park (WONIK IPS, Korea), Misoo Kim, Khabib Khumaini, Hye-Lee Kim, Gyejun Cho, Yewon Kim, Won-Jun Lee (Sejong Univ., Korea), and Min Kim (WONIK IPS, Korea)

### [WeB2-4]

15:20-15:35

#### **Study on SiO<sub>2</sub> Atomic Scale Etching Using Selective Control of Ar Metastable Atom Generation**

Chang-Min Lim, Jae-Hwi Kim, Hyeon-Jun Cho, Young Don Kim, and Chin-Wook Chung (Hanyang Univ., Korea)